

## DESCRIPTION

COATING FILM HAVING LOW REFRACTIVE INDEX AND LARGE  
CONTACT ANGLE WITH WATER

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## TECHNICAL FIELD

The present invention relates to an improvement of a coating film formed on a substrate from a polymer solution of alkoxy group-containing silicon compounds.

10 Particularly, the present invention relates to a coating film having a low refractive index and a large contact angle with water, which is formed as adhered to a substrate surface by heat-curing on the substrate surface a coating comprising a solution of a polysiloxane

15 prepared by co-polycondensing alkoxy group-containing silicon compounds having a specific composition, in the absence of water.

## BACKGROUND ART

20 It is known that when a coating film showing a refractive index lower than the refractive index of a substrate is formed on the surface of the substrate, the reflectance of light reflected from the surface of the coating film decreases. Such a coating film showing a

25 decreased light reflectance is utilized as an antireflection film and practically applied to various substrate surfaces.

A process for forming an antireflection film having a low refractive index, on a substrate, is disclosed which comprises applying on a glass substrate such as a cathode ray tube an alcohol dispersion of fine particles of  $\text{MgF}_2$  formed by reacting a magnesium salt or an alkoxy magnesium compound as a Mg source with a fluoride salt as a F source, or a liquid having tetraalkoxysilane or the like added thereto for improving the film strength, as a coating fluid, followed by heat-treatment at a temperature of from  $100^\circ\text{C}$  to  $500^\circ\text{C}$  (Patent Document 1).

A low reflection glass having formed on a glass substrate a thin film showing a refractive index of from 1.21 to 1.40 and having a thickness of from 60 to 160 nm with irregularities or micro-pits having a diameter of from 50 to 200 nm, is disclosed, wherein the film is formed by mixing a solvent such as an alcohol with at least two hydrolytic polycondensates different in the average molecular weight, such as tetraalkoxysilane, methyltrialkoxysilane, to obtain a coating fluid, forming a coating film from such a coating fluid by controlling the relative humidity and the mixing ratio at the time of the above mixing, and heating the coating film (Patent Document 2).

A low reflectance glass comprising a glass, a lower layer film having a high refractive index formed on its surface and an upper layer film having a low refractive index formed on the surface thereof, is disclosed (Patent

Document 3). As a detailed description of the process for forming the upper layer film, this publication discloses a process which comprises hydrolyzing a fluorine-containing silicone compound having a polyfluorocarbon chain such as  $\text{CF}_3(\text{CF}_2)_2\text{C}_2\text{H}_4\text{Si}(\text{OCH}_3)_3$  and a silane coupling agent such as  $\text{Si}(\text{OCH}_3)_4$  in an amount of from 5 to 90 wt% based thereon, in an alcohol solvent in the presence of a catalyst such as acetic acid, followed by filtration to obtain a liquid of a co-polycondensate, then applying this liquid on the lower layer film and heating it at a temperature of from 120 to 250°C.

A coating film having a refractive index of from 1.28 to 1.38 and a contact angle with water of from 90° to 115°, is disclosed which is formed as adhered on a substrate surface, by preparing a reaction mixture comprising a silicon compound of the formula  $\text{Si}(\text{OR})_4$ , a silicon compound of the formula  $\text{CF}_3(\text{CF}_2)_n\text{CH}_2\text{CH}_2\text{Si}(\text{OR}^1)_3$ , an alcohol of the formula  $\text{R}^2\text{CH}_2\text{OH}$  and oxalic acid in a specific ratio, heating this reaction mixture at a temperature of from 40 to 180°C in the absence of water to form a solution of a polysiloxane, applying a coating fluid containing the solution on a substrate surface to form a coating, and heat-curing the coating at a temperature of from 80 to 450°C (Patent Document 4).

Patent Document 1: JP-A-05-105424

Patent Document 2: JP-A-06-157076

Patent Document 3: JP-A-61-010043

## DISCLOSURE OF THE INVENTION

## PROBLEMS TO BE SOLVED BY THE INVENTION

5       The process for forming a multilayer coating film on  
a substrate as disclosed in the above Patent Document 3,  
requires repetition of the coating and baking steps, and  
is not efficient. Besides, due to repetition of the  
baking step, cracks are likely to form in the coating  
10 film, the resulting coating film tends to be non-uniform,  
and deformation of the substrate is likely to occur.  
Further, in order to impart a low refractive index to the  
upper layer film formed from the coating fluid obtained  
by such as hydrolytic method, it is required to use a  
15 large amount of the fluorine-containing silicone compound  
at a level of at least 1.1 mol per mol of the silane  
coupling agent, and even in such a case, a coating film  
having a refractive index lower than 1.33 is hardly  
obtainable. Further, if the coating fluid obtained by  
20 such a hydrolytic method, is directly applied on the  
substrate, and the coating is heated, the resulting  
coating film, will not have sufficient hardness.

By the process disclosed in the above Patent  
Document 1, the bond strength among the fine particles of  
25  $\text{MgF}_2$  is weak, so that the formed coating film is poor in  
the mechanical strength, and the adhesive strength to the  
substrate is inadequate. Besides, this coating film made

of  $\text{MgF}_2$  does not essentially show a refractive index lower than 1.38, and depending upon the type of the substrate, no adequate antireflection property can be obtained. The process disclosed in the above Patent Document 2 is cumbersome in the preparation and incorporation of the polycondensates having different molecular weights and further requires control of the relative humidity during the film-forming and the surface irregularities of the coating film. Thus, this process is not practically useful.

Each of the coating films disclosed in the above Patent Documents 1 and 2 is susceptible to staining of its surface during practical use, and to prevent such staining, it has been common to apply a treating agent having higher water repellency on its surface, such as a stain-proofing agent made of a fluorine-containing compound.

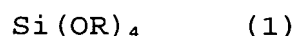
The coating film disclosed in the Patent Document 4 forms a highly hard and highly water repellent low reflection coating film when applied to a plastic film having irregularities formed on its surface, like an antiglare-treated hard coat-covered triacetylcellulose (TAC) film. However, the hardness tends to be inadequate when it is formed on a film having a smooth surface such as a clear hard coat-covered TAC film.

It is an object of the present invention to provide a process for simply and efficiently forming an improved

coating film on a substrate, particularly to provide a coating film formed on a substrate, as adhered to the surface of the substrate and having a refractive index of from 1.28 to 1.38 and a contact angle with water of from 90° to 115°.

#### MEANS TO SOLVE THE PROBLEMS

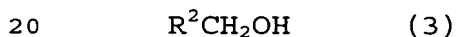
The coating film of the present invention is a coating film having a refractive index of from 1.28 to 1.38 and a contact angle with water of from 90° to 115°, which is formed as adhered to a substrate surface by forming a reaction mixture comprising a silicon compound (A) of the formula (1):



wherein R is a C<sub>1-5</sub> alkyl group, a silicon compound (B) of the formula (2):



wherein R<sup>1</sup> is a C<sub>1-5</sub> alkyl group, and n is an integer of from 1 to 13, an alcohol (C) of the formula (3):



wherein R<sup>2</sup> is a hydrogen atom or a C<sub>1-12</sub> alkyl group (the alkyl group may optionally be substituted by one or more substituents of the same or different types selected from the group consisting of a C<sub>1-3</sub> alkyl group, a C<sub>1-3</sub> hydroxyalkyl group, a C<sub>2-6</sub> alkoxyalkyl group, a C<sub>2-6</sub> hydroxyalkoxyalkyl group and a C<sub>3-6</sub> alkoxyalkoxyalkyl group), and oxalic acid (D), in a ratio of from 0.05 to

0.43 mol of the silicon compound (B) per mol of the silicon compound (A), in a ratio of from 0.5 to 100 mol of the alcohol (C) per mol of the total alkoxy groups contained in the silicon compounds (A) and (B) and in a ratio of 0.2 to 2 mol of the oxalic acid (D) per mol of the total alkoxy groups contained in the silicon compounds (A) and (B); heating this reaction mixture at a temperature of from 50 to 180°C until the total amount of the silicon compounds (A) and (B) remaining in the reaction mixture becomes at most 5 mol%, while it is maintained at a SiO<sub>2</sub> concentration of from 0.5 to 10 wt% as calculated from silicon atoms in the reaction mixture and while absence of water is maintained, to form a solution of a polysiloxane thereby formed; then applying a coating fluid comprising the polysiloxane solution on a substrate surface to form a coating; and heat-curing the coating at a temperature of from 80 to 450°C.

The above mentioned polysiloxane solution is transparent and contains no gelled polysiloxane. This polysiloxane is not one formed by condensation of hydrolysates of the silicon compounds (A) and (B), since the silicon compounds (A) and (B) are heated in a reaction mixture wherein no water is present, although a large amount of the alcohol (C) and a relatively large amount of oxalic acid (D) are present. When a polysiloxane is formed from an alkoxy silane by hydrolysis in an alcohol solvent, it is likely that the liquid will

be turbid as the hydrolysis proceeds, or a non-uniform polysiloxane will form. However, with the above reaction mixture by the present invention, no such a phenomenon will take place.

5        With respect to the above polysiloxane by the present invention, its chemical structure is complex and can hardly be specified. However, it is considered that the polymerization proceeds as the alcohol (C) will act on an intermediate formed by a reaction of the silicon  
10    compounds (A) and (B) with the oxalic acid (D), whereby a co-polycondensate polysiloxane of the silicon compounds (A) and (B) will be formed which has a polymerization degree of a level to form a solution and which has a relatively uniform structure, although it may have a  
15    branched structure.

      By heating a coating containing the above polysiloxane solution applied on the substrate, removal of a volatile component from the coating and a curing reaction of the polysiloxane in the coating will proceed  
20    thereby to form an insoluble coating film as adhered to the substrate surface and having a low refractive index and water repellency.

      As the molar ratio of the amount of the silicon compound (B) to the amount of the silicon compound (A)  
25    becomes large, the refractive index of this coating film becomes low, and the contact angle with water becomes large. However, as is different from the upper layer



film disclosed in the above Patent Document 3, the coating film of the present invention has a refractive index lower than the refractive index of such an upper layer film, in spite of the fact that it is formed from a coating fluid having a low content of the silicon compound (B).

#### EFFECTS OF THE INVENTION

The polysiloxane solution to be used for forming the coating film of the present invention has stability durable for storage for about six months at room temperature and thus may be presented as an industrial product. And, the coating film of the present invention can easily be obtained by a step of applying on a substrate surface a coating fluid comprising such a solution as the industrial product and a step of heat-curing the coating.

By forming the coating film of the present invention on a substrate having a refractive index higher than the refractive index of the coating film of the present invention, such as on a usual glass surface, it is easily possible to convert such a substrate to an antireflective substrate. The thickness of the coating film of the present invention may be adjusted by the thickness of the coating, but it can easily be adjusted by adjusting the  $\text{SiO}_2$  concentration in the coating fluid. The coating film of the present invention may be used effectively as

a single coating film on the substrate surface, but it may also be used as an upper layer coating film on a lower layer coating film having a high refractive index.

It is known that a relational expression of

5  $d = (2b-1)\lambda/4a$  (wherein  $b$  is an integer of at least 1) is satisfied between the thickness  $d$  (nm) of the coating film having a refractive index  $a$  and the wavelength  $\lambda$  (nm) of light, of which a decrease in reflectance by this coating film is desired. Accordingly, by setting the

10 thickness of the coating film by utilizing this expression, it is readily possible to prevent reflection of any desired light. For example, it is easily possible to accomplish prevention of reflection from a glass surface of light having a center wavelength 550 nm of

15 visible light by a coating film having a refractive index of 1.32, by adopting a coating film thickness of 104 nm obtained by substituting such numerical values for  $\lambda$  and  $a$  in the above formula and substituting 1 for  $b$ , or a coating film thickness of 312 nm obtained by substituting

20 2 for  $b$ . The coating film of the present invention can be applied to the surface of a cathode ray tube made of glass, a display of a computer, a mirror having a glass surface, a showcase made of glass or various other products, which are desired to have reflection of light

25 prevented. The coating film of the present invention is highly hard and excellent in scratch resistance and has a practically sufficient antifouling property, and it can

be formed by baking at a low temperature at a level of about 100°C. Accordingly, it is useful particularly for an antireflection film for a liquid crystal TV or a display monitor.

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#### BEST MODE FOR CARRYING OUT THE INVENTION

Examples of the alkyl group R in the above formula (1) include methyl, ethyl, propyl, butyl and pentyl.

Preferred examples of the silicon compound (A) include  
10 tetramethoxysilane, tetraethoxysilane, tetrapropoxysilane and tetrabutoxysilane. Among them, particularly preferred are tetramethoxysilane and tetraethoxysilane.

Examples of the alkyl group R<sup>1</sup> in the above formula (2) include methyl, ethyl, propyl, butyl and pentyl.

15 Preferred examples of the silicon compound (B) include 1,1-bis(trimethoxysilylethyl)perfluoromethane, 1,1-bis(triethoxysilylethyl)perfluoromethane, 1,2-bis(trimethoxysilylethyl)perfluoroethane, 1,2-bis(triethoxysilylethyl)perfluoroethane, 1,3-bis(trimethoxysilylethyl)perfluoropropane, 1,3-bis(triethoxysilylethyl)perfluoropropane, 1,4-bis(trimethoxysilylethyl)perfluorobutane, 1,4-bis(triethoxysilylethyl)perfluorobutane, 1,5-bis(trimethoxysilylethyl)perfluoropentane, 1,5-bis(triethoxysilylethyl)perfluoropentane, 1,6-bis(trimethoxysilylethyl)perfluorohexane, 1,6-bis(triethoxysilylethyl)perfluorohexane, 1,7-bis(trimethoxysilylethyl)perfluorohexane, 1,7-

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bis(trimethoxysilylethyl)perfluoroheptane, 1,7-bis(triethoxysilylethyl)perfluoroheptane, 1,8-bis(trimethoxysilylethyl)perfluorooctane and 1,8-bis(triethoxysilylethyl)perfluorooctane. These compounds  
5 may be used alone or in combination as a mixture of two or more of them.

Examples of the unsubstituted alkyl group  $R^2$  in the above formula (3) include methyl, ethyl, propyl, butyl, pentyl, hexyl, heptyl and octyl. Examples of the  
10 substituted alkyl group  $R^2$  include hydroxymethyl, methoxymethyl, ethoxymethyl, hydroxyethyl, methoxyethyl, ethoxyethyl, methoxyethoxymethyl and ethoxyethoxymethyl. Preferred examples of the alcohol (C) include methanol, ethanol, propanol, n-butanol, ethylene glycol monomethyl  
15 ether, ethylene glycol monoethyl ether, diethylene glycol monomethyl ether and diethylene glycol monoethyl ether. These alcohols may be used alone or in combination as a mixture of two or more of them. Among them, particularly preferred are methanol and ethanol.

20 A uniform polysiloxane solution is hardly obtainable from a reaction mixture in which the silicon compound (B) is used in an amount exceeding 0.43 mol per mol of the silicon compound (A). From a reaction mixture wherein the silicon compound (B) is used in an amount of less  
25 than 0.05 mol per mol of the silicon compound (A), a coating film having a refractive index of 1.38 or less will hardly be formed, and the coating film thereby

formed will not exhibit water repellency showing a contact angle with water of at least  $90^\circ$ . It is particularly preferred that the silicon compound (B) is used in an amount of from 0.05 to 0.25 mol per mol of the silicon compound (A).

If the alcohol is used in an amount less than 0.5 mol per mol of the total alkoxy groups contained in the silicon compounds (A) and (B), it takes a long time to form the polysiloxane, and it tends to be difficult to form a coating film having high hardness from the liquid containing the polysiloxane thereby obtained. On the other hand, if the alcohol is used in an amount more than 100 mol per mol of the total alkoxy groups contained in the silicon compounds (A) and (B), the  $\text{SiO}_2$  concentration in the obtained polysiloxane-containing liquid tends to be inadequate, and concentration will be required prior to coating, such being inefficient. It is particularly preferred to use the alcohol in an amount of from 1 to 50 mol per mol of the total alkoxy groups contained in the silicon compounds (A) and (B).

If oxalic acid (D) is used in an amount smaller than 0.2 mol per mol of the total alkoxy groups contained in the silicon compounds (A) and (B), it tends to be difficult to form a coating film having high hardness from the resulting polysiloxane-containing liquid. On the other hand, if the oxalic acid (D) is used in an amount more than 2 mol per mol of the total alkoxy groups

contained in the silicon compounds (A) and (B), the resulting polysiloxane-containing liquid contains a relatively large amount of the oxalic acid (D), and from such a liquid, it tends to be difficult to obtain a  
5 coating film having the desired properties. It is particularly preferred to use the oxalic acid (D) in an amount of from 0.25 to 1 mol per mol of the total alkoxy groups contained in the silicon compounds (A) and (B).

In the formation of the reaction mixture, an  
10 alkylalkoxysilane may be incorporated as a modifier (E), for example, in an amount of from 0.02 to 0.2 mol per mol of the silicon compound (A), as the case requires, in addition to the silicon compounds (A) and (B), the alcohol (C) and the oxalic acid (D). Preferred examples  
15 of the modifier (E) include trialkoxysilanes such as methyltrimethoxysilane, methyltriethoxysilane, ethyltrimethoxysilane, ethyltriethoxysilane, propyltrimethoxysilane, propyltriethoxysilane, butyltrimethoxysilane, butyltriethoxysilane,  
20 pentyltrimethoxysilane, pentyltriethoxysilane, heptyltrimethoxysilane, heptyltriethoxysilane, octyltrimethoxysilane, octyltriethoxysilane, dodecyltrimethoxysilane, dodecyltriethoxysilane, hexadecyltrimethoxysilane, hexadecyltriethoxysilane,  
25 octadecyltrimethoxysilane, octadecyltriethoxysilane, phenyltrimethoxysilane, phenyltriethoxysilane, vinyltrimethoxysilane, vinyltriethoxysilane,  $\gamma$ -

aminopropyltrimethoxysilane,  $\gamma$ -  
aminopropyltriethoxysilane,  $\gamma$ -  
glycidoxypropyltrimethoxysilane,  $\gamma$ -  
glycidoxypropyltriethoxysilane,  $\gamma$ -  
5 methacryloxypropyltrimethoxysilane and  $\gamma$ -  
methacryloxypropyltriethoxysilane,  $\gamma$ -  
ureidopropyltrimethoxysilane,  $\gamma$ -  
ureidopropyltriethoxysilane, and dialkoxysilanes such as  
dimethyldimethoxysilane and dimethyldiethoxysilane, and  
10 trialkoxysilanes such as trimethylmethoxysilane and  
trimethylethoxysilane. These modifiers may be used alone  
or in combination as a mixture of two or more of them.

Such a modifier (E) is capable of lowering the  
temperature for curing the coating on the substrate and  
15 improves the adhesion of the coating film to the  
substrate. The reaction mixture comprising the silicon  
compounds (A) and (B), the alcohol (C) and the oxalic  
acid (D) may be formed by mixing such components, or by  
further incorporating the above modifier (E) thereto. To  
20 such a reaction mixture, no water may be added. This  
reaction mixture is preferably heated in the form of a  
solution. For example, it is preferably heated as a  
reaction mixture in the form of a solution obtained by  
preliminarily adding the oxalic acid (D) to the alcohol  
25 (C) to form an alcohol solution of oxalic acid and then  
mixing the silicon compounds (A) and (B) and the above  
modifier (E). The reaction mixture comprising the

silicon compounds (A) and (B), the alcohol (C) and the oxalic acid (D) in the above mentioned ratio, usually has a  $\text{SiO}_2$  concentration of from 0.5 to 10 wt% when silicon atoms contained therein are calculated as  $\text{SiO}_2$ . Also in  
5 the case of the reaction mixture containing the above modifier (E), such a modifier (E) is incorporated so that the mixture will have a  $\text{SiO}_2$  concentration of from 0.5 to 10 wt% when silicon atoms contained therein are calculated as  $\text{SiO}_2$ . Such a reaction mixture is  
10 maintained at the above  $\text{SiO}_2$  concentration and in the absence of water during the heating of the reaction mixture. This heating can be carried out in a usual reactor at a liquid temperature of from 50 to 180°C. Preferably, it is carried out, for example, in a closed  
15 container or under reflux, so that no evaporation or volatilization of the liquid from the reactor occurs.

In the formation of the reaction mixture, a fluoroalkyl group-containing alkylalkoxysilane (F) may be used in combination with the silicon compound (B), for  
20 example, in such an amount that the total amount of the silicon compound (B) and the fluoroalkyl group-containing alkoxysilane (F) will be from about 0.05 to 0.43 mol per mol of the silicon compound (A), as the case requires, in addition to the silicon compounds (A) and (B), the  
25 alcohol (C), the oxalic acid (D), etc. Preferred examples of the fluoroalkyl group-containing alkylalkoxysilane (F) include



trifluoropropyltrimethoxysilane,  
trifluoropropyltriethoxysilane,  
tridecafluorooctyltrimethoxysilane,  
tridecafluorooctyltriethoxysilane,  
5 heptadecafluorodecyltrimethoxysilane and  
heptadecafluorodecyltriethoxysilane, and they may be used  
alone or in combination as a mixture of two or more of  
them.

Such a fluoroalkyl group-containing  
10 alkylalkoxysilane (F) is capable of suppressing an  
excessive copolymerization reaction of the silicon  
compounds (A) and (B) thereby to form a polysiloxane  
solution which can be stored for a long period of time.  
The reaction mixture comprising the silicon compounds (A)  
15 and (B), the alcohol (C) and the oxalic acid (D) may be  
formed by mixing such components, or by further  
incorporating the above fluoroalkyl group-containing  
alkylalkoxysilane (F) thereto. To such a reaction  
mixture, no water may be added. This reaction mixture is  
20 preferably heated in the form of a solution. For  
example, it is preferably heated as a reaction mixture in  
the form of a solution obtained by preliminarily adding  
the oxalic acid (D) to the alcohol (C) to form an alcohol  
solution of oxalic acid and then mixing such a solution  
25 with the silicon compounds (A) and (B), the above  
fluoroalkyl group-containing alkoxysilane (F), etc. The  
reaction mixture comprising the silicon compounds (A) and

(B), the alcohol (C) and the oxalic acid (D) in the above mentioned ratio, usually has a  $\text{SiO}_2$  concentration of from 0.5 to 10 wt% when silicon atoms contained therein are calculated as  $\text{SiO}_2$ . Also in the case of the reaction mixture containing the above fluoroalkyl group-containing alkylalkoxysilane (F), such a fluoroalkyl group-containing alkylalkoxysilane (F) is incorporated so that the mixture will have a  $\text{SiO}_2$  concentration of from 0.5 to 10 wt% when silicon atoms contained therein are calculated as  $\text{SiO}_2$ . Such a reaction mixture is maintained at the above  $\text{SiO}_2$  concentration and in the absence of water during the heating of the reaction mixture. This heating can be carried out in a usually reactor at a liquid temperature of from 50 to 180°C. Preferably, it is carried out, for example, in a closed container or under reflux, so that no evaporation or volatilization of the liquid from the reactor occurs.

If the heating to form the polysiloxane is carried out at a temperature lower than 50°C, the liquid tends to have turbidity or tends to contain insoluble substances. Therefore, this heating is carried out at a temperature higher than 50°C. If the temperature is high, the operation can be completed in a short period of time. However, heating at a temperature higher than 180°C is inefficient, as no additional merits will be thereby obtained. The heating time is not particularly limited. For example, it is usually about 8 hours at 50°C and

about 3 hours under reflux at 78°C. Usually, the heating is terminated when the amount of the remaining silicon compounds (A) and (B) becomes at most 5 mol%, based on the total charge amount of the silicon compounds (A) and (B). If a polysiloxane-containing liquid in which these silicon compounds remain more than 5% based on the total amount of the silicon compounds (A) and (B) charged, is applied on a substrate surface and then the coating is heat-cured at a temperature of from 80 to 450°C, the resulting coating film tends to have pinholes, or it tends to be difficult to obtain a coating film having adequate hardness.

The polysiloxane solution obtained by the above heating, may be used directly as a coating fluid for the next coating step. However, if desired, it may be concentrated or diluted to obtain a solution useful as a coating fluid, or the solvent may be substituted by other solvent to obtain a solution useful as a coating fluid. Otherwise, an optional additive (G) may be added thereto to obtain a coating fluid. Examples of such an additive (G) include a silica sol, an alumina sol, a titania sol, a zirconia sol, a magnesium fluoride sol and a ceria sol, which are in the form of sols of colloidal inorganic fine particles. These sols may be used alone or in combination as a mixture of two or more of them. Such sols are preferably organo sols. Particularly preferred are organo sols using the alcohol (C) as the dispersing

medium. The amount of the sol to be added, may be selected optionally, so long as the amount of colloidal inorganic fine particles is at most 70 wt%, based on the total weight of the heat cured solid content in the coating fluid. As other additives (G), metal salts or metal compounds may, for example, be mentioned. These additives are suitable for controlling the water repellency of the coating film.

The coating fluid to be used in the coating step, is preferably a fluid which contains from 0.5 to 10 wt%, as calculated as  $\text{SiO}_2$  of silicon atoms derived from the above polysiloxane transparent solution. If this  $\text{SiO}_2$  concentration is less than 0.5%, the thickness of the coating film formed by one coating operation tends to be thin. If the concentration exceeds 10 wt%, the storage stability of such a coating fluid tends to be inadequate. It is particularly preferred that the  $\text{SiO}_2$  concentration of this coating fluid is from 2 to 8 wt%.

The substrate is not particularly limited so long as it permits formation of an adhesive coating film thereon. In order to form an antireflection coating film thereon, it is preferred to use a substrate having a refractive index higher than the refractive index of the coating film, such as usual glass or plastics. The above polysiloxane solution or a coating fluid comprising such as solution, can be applied on the substrate by a conventional method such as a dipping method, a spin

coating method, a brush coating method, a roll coating method or a flexo printing method.

The coating formed on the substrate may directly be heat-cured. However, prior to such heat-curing, it may  
5 be dried at a temperature of from room temperature to 80°C, preferably from 50 to 80°C, and then heated at a temperature of from 80 to 450°C, preferably from 100 to 450°C. The time for this heating may be from 5 to 60 minutes for adequate heat-curing. If this heating  
10 temperature is lower than 80°C, the hardness, chemical resistance or the like of the resulting coating film tends to be inadequate. In the case of a heat resistant substrate such as glass, heating may usually be carried out at a temperature of at least 300°C. However, at a  
15 temperature higher than 450°C, no adequate water repellency tends to be imparted to the resulting coating film. Such heating can be carried out by a conventional method, for example, by using a hot plate, an oven or a belt furnace.

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#### EXAMPLES

Now, the present invention will be described with reference to Examples. However, it should be understood that the present invention is by no means restricted to  
25 such Examples.

#### GAS CHROMATOGRAPHY (GC)

In Examples 1, 2, 3 and 4, and Comparative Example

1, the remaining alkoxysilane monomer after the reaction was confirmed by means of gas chromatography.

Conditions for gas chromatography: Apparatus:

Shimadzu GC-14B, column: capillary column CBP1-W25-100

5 (25 mm  $\times$  0.53 mm  $\phi$   $\times$  1  $\mu$ m), column temperature: the column temperature was controlled by using a temperature raising program. The temperature was raised from the initial temperature of 50°C at a rate of 15°C/min to the ultimate temperature of 290°C (3 minutes).

10 Injected amount of sample: 1  $\mu$ m, injection temperature: 240°C, detector temperature: 290°C, carrier gas: nitrogen (flow rate 30 mL/min), detection method: FID method.

#### EXAMPLE 1

15 72.1 g of methanol was charged into a four-necked reaction flask equipped with a reflux condenser, and 12.1 g of oxalic acid was gradually added to this methanol with stirring, to prepare a methanol solution of oxalic acid. Then, this solution was heated to its reflux  
20 temperature, and a mixture comprising 8.4 g of tetraethoxysilane and 7.4 g of 1,6-bis(trimethoxysilyl)ethylperfluorohexane, was dropwise added to this solution under reflux. After completion of the dropwise addition, heating under reflux was continued  
25 for 5 hours, followed by cooling to obtain a polysiloxane solution (L<sub>1</sub>).

This solution (L<sub>1</sub>) was analyzed by gas

chromatography, whereby no alkoxy silane monomer was detected. This solution ( $L_1$ ) was applied on the surface of a calcium fluoride substrate, and then the coating was heated at 300°C for 30 minutes to form a coating film  
5 adhered to the surface of this calcium fluoride substrate. Then, with respect to this coating film, the spectrum of transmitted light was measured by means of an infrared spectroscope, whereby absorption by a silanol group was observed in the vicinity of 3,200  $\text{cm}^{-1}$  and in  
10 the vicinity of 980  $\text{cm}^{-1}$ , absorption by a methylene group was observed in the vicinity of 2,800  $\text{cm}^{-1}$ , absorption by Si-O-Si was observed in the vicinity of 1,100  $\text{cm}^{-1}$ , and absorption by C-F was observed in the vicinity of 1,200  $\text{cm}^{-1}$ .

## 15 EXAMPLE 2

71.3 g of ethanol was charged into a four-necked reaction flask equipped with a reflux condenser, and 12.1 g of oxalic acid was gradually added to this ethanol with stirring, to prepare an ethanol solution of oxalic acid.  
20 Then, this solution was heated to its reflux temperature, and a mixture comprising 9.8 g of tetraethoxysilane, 3.1 g of tridecafluorooctyltrimethoxysilane and 3.7 g of 1,6-bis(trimethoxysilyl)ethylperfluorohexane, was dropwise added to this solution under reflux. After completion of  
25 the dropwise addition, heating was continued for 5 hours under reflux, followed by cooling to obtain a polysiloxane solution ( $L_2$ ).

This solution (L<sub>2</sub>) was analyzed by gas chromatography, whereby no alkoxysilane monomer was detected.

#### EXAMPLE 3

5        71.1 g of ethanol was charged into a four-necked reaction flask equipped with a reflux condenser, and 12.1 g of oxalic acid was gradually added to this ethanol with stirring, to prepare an ethanol solution of oxalic acid. Then, this solution was heated to its reflux temperature, and a mixture comprising 8.1 g of tetraethoxysilane, 3.1 g of tridecafluorooctyltrimethoxysilane, 3.7 g of 1,6-bis(trimethoxysilylethyl)perfluorohexane, 1.3 g of  $\gamma$ -glycidoxypropyltrimethoxysilane and 0.6 g of  $\gamma$ -aminopropyltrimethoxysilane, was dropwise added to this  
10 solution under reflux. After completion of the dropwise addition, heating was continued for 5 hours under reflux, followed by cooling to obtain a polysiloxane solution (L<sub>3</sub>). This solution (L<sub>3</sub>) was analyzed by gas chromatography, whereby no alkoxide monomer was detected.

#### 20    EXAMPLE 4

67.5 g of methanol was charged into a four-necked reaction flask equipped with a reflux condenser, and 12.1 g of oxalic acid was gradually added to this methanol with stirring, to prepare a methanol solution of oxalic  
25 acid. Then, this solution was heated to its reflux temperature, and a mixture comprising 9.1 g of tetraethoxysilane, 3.1 g of



tridecafluorooctyltrimethoxysilane, 3.7 g of 1,6-bis(trimethoxysilylethyl)perfluorohexane, 0.9 g of  $\gamma$ -ureidopropyltriethoxysilane and 3.6 g of methanol, was dropwise added to this solution under reflux. After completion of the dropwise addition, heating was continued for 5 hours under reflux, followed by cooling to obtain a polysiloxane solution ( $L_4$ ). This solution ( $L_4$ ) was analyzed by gas chromatography, whereby no alkoxide monomer was detected.

10 EXAMPLE 5

To 25.0 g of the solution ( $L_3$ ) obtained in Example 3, 19.1 g of a methanol-dispersed silica sol containing 15.7 wt% as  $SiO_2$  of colloidal silica having a particle size of 8 nm, and 55.9 g of ethanol, were added and thoroughly mixed to obtain a polysiloxane solution ( $L_5$ ).

COMPARATIVE EXAMPLE 1

70.6 g of ethanol was charged into a four-necked reaction flask equipped with a reflux condenser, and 12.0 g of oxalic acid was gradually added to this ethanol with stirring, to prepare an ethanol solution of oxalic acid. Then, this solution was heated to its reflux temperature, and a mixture comprising 9.4 g of tetraethoxysilane, 6.2 g of tridecafluorooctyltrimethoxysilane [ $CF_3C_5F_{10}C_2H_4Si(OCH_3)_3$ ], 1.2 g of  $\gamma$ -glycidoxypropyltrimethoxysilane and 0.6 g of  $\gamma$ -aminopropyltrimethoxysilane, was dropwise added to this solution under reflux. After completion of the dropwise

addition, heating was continued for 5 hours under reflux, followed by cooling to obtain a polysiloxane solution ( $L_6$ ). This solution ( $L_6$ ) was analyzed by gas chromatography, whereby no alkoxide monomer was detected.

5 COMPARATIVE EXAMPLE 2

To 25.0 g of the solution ( $L_6$ ) obtained in Comparative Example 1, 19.1 g of a methanol-dispersed silica sol containing 15.7 wt% as  $SiO_2$  of colloidal silica having a particle size of 8 nm, and 55.9 g of  
10 ethanol, were added and thoroughly mixed to obtain a polysiloxane solution ( $L_7$ ).

COMPARATIVE EXAMPLE 3

Into a four-necked reaction flask equipped with a reflux condenser, a mixture comprising 58.7 g of ethanol,  
15 8.4 g of tetraethoxysilane and 7.4 g of 1,6-bis(trimethoxysilylethyl)perfluorohexane, was charged and mixed to prepare an ethanol solution of the alkoxysilanes. Then, this solution was heated to its reflux temperature, and a mixture comprising 20.0 g of  
20 ethanol, 5.4 g of water and 0.1 g of 60% nitric acid as a catalyst, was dropwise added to this solution under reflux. After completion of the dropwise addition, the heating was continued for 5 hours under reflux, followed by cooling to obtain a solution ( $L_8$ ) containing  
25 hydrolysates of alkoxysilanes.

EXAMPLE 6

Each of the above liquids ( $L_1$ ) to ( $L_8$ ) was used as a

coating fluid, and coating was formed by means of a bar coater on a hard coat-covered TAC film (80  $\mu\text{m}$ , reflectance: 4.5%) manufactured by Nippon Paper Industries Co., Ltd. surface-treated by the following method, and then dried at room temperature for 30 minutes. It was further heated in a clean oven for one hour at the temperature shown in Table 1, to form a coating film on the substrate surface. Then, with respect to each coating film thus obtained, measurements of the refractive index, the reflectance and the contact angle with water, and tests for oil-based ink wiping efficiency and finger print wiping efficiency, were carried out by the following methods. For the measurement of the refractive index, the coating film was formed by spin coating on a silicon substrate.

#### METHOD FOR SURFACE TREATMENT OF TAC FILM

A hard coat-covered TAC film manufactured by Nippon Paper Industries Co., Ltd. was immersed in a 5 wt% potassium hydroxide (KOH) aqueous solution heated to 40°C for 3 minutes for alkali treatment, then washed with water and then immersed in a 0.5 wt% sulfuric acid ( $\text{H}_2\text{SO}_4$ ) aqueous solution at room temperature for 30 minute for neutralization, followed by washing with water and drying.

#### METHOD FOR MEASURING REFRACTIVE INDEX

Using Ellipsometer DVA-36L, manufactured by Mizojiri Kogaku K. K., the refractive index of light with a

wavelength of 633 nm was measured.

#### METHOD FOR MEASURING REFLECTANCE

Using spectrophotometer UV 3100 PC, manufactured by Shimadzu Corporation, the reflectance of light with a  
5 wavelength of 550 nm was measured at an angle of incidence of 5°.

#### METHOD FOR MEASURING CONTACT ANGLE WITH WATER

Using an automatic contact angle meter CA-Z model, manufactured by Kyowa Kaimen Kagaku K.K., the contact  
10 angle when 3  $\mu$ l of pure water was dropped, was measured.

#### OIL-BASED INK WIPING TEST

Using an oil-based ink pen, manufactured by PENTEL CO., LTD., an ink drawn on a substrate surface, was wiped off by means of BEMCOT M-3, manufactured by Asahi Kasei  
15 Corporation, whereby the wiping off efficiency was visually evaluated. The evaluation standards are as follows.

A: Ink can completely be wiped off. B: Ink can be wiped off, but a trace will remain. C: Ink can not be  
20 wiped off.

#### FINGER PRINT WIPING TEST

A finger print on a substrate surface was wiped off by means of BEMCOT M-3, manufactured by Asahi Kasei Corporation, whereby the wiping off efficiency was  
25 visually evaluated.

The evaluation standards are as follows.

A: The finger print can be completely wiped off. B:

The finger print can be wiped off, but a trace will remain, or the trace may be removed but the finger print will stretch. C: The finger print can not be wiped off.

#### ABRASION RESISTANCE

5 Steel wool #0000, manufactured by Nippon Steel Wool K.K. was reciprocated ten times for abrasion under a load of  $200 \text{ g/cm}^2$  or  $500 \text{ g/cm}^2$ , whereupon scratch marks were visually evaluated.

The evaluation standards are as follows.

10 A: No scratch observed. B: Less than ten scratch marks observed. C: From 10 to 30 scratch marks observed. D: More than 30 scratch marks observed.

#### ADHESION

A cured coating film on a substrate was cross-cut at  
15 1 mm intervals for 100 sections, and an adhesive tape (trade name: Cellotape, manufactured by NICHIBAN CO., LTD., 24 mm) was firmly bonded to the cured coating film and then, the adhesive tape was rapidly peeled, whereupon the presence or absence of peeling of the cured film was  
20 visually observed.

TABLE 1

Coating fluid	Temperature for curing (°C)	Refractive index	Reflectance (%)	Abrasion resistance	
				200 g	500 g
L <sub>1</sub>	100	1.36	1.2	B	C
L <sub>2</sub>	100	1.36	1.2	B	D
L <sub>3</sub>	70	1.38	1.8	B	D
L <sub>3</sub>	100	1.38	1.8	A	C
L <sub>3</sub>	120	1.38	1.8	A	B
L <sub>4</sub>	100	1.37	1.4	A	A
L <sub>5</sub>	100	1.39	1.9	B	D
L <sub>6</sub>	100	1.38	1.7	D	D
L <sub>7</sub>	100	1.39	1.9	C	D
L <sub>8</sub>	100	1.39	1.9	C	D

TABLE 2

Coating fluid	Temperature for curing (°C)	Contact angle with water (°)	Oil-based ink wiping efficiency	Finger pint wiping efficiency	Adhesion
L <sub>1</sub>	100	104	A	A	100/100
L <sub>2</sub>	100	104	A	A	100/100
L <sub>3</sub>	70	105	A	A	100/100
L <sub>3</sub>	100	105	A	A	100/100
L <sub>3</sub>	120	105	A	A	100/100
L <sub>4</sub>	100	104	A	A	100/100
L <sub>5</sub>	100	105	A	A	100/100
L <sub>6</sub>	100	104	A	A	100/100
L <sub>7</sub>	100	102	B	A	100/100
L <sub>8</sub>	100	100	B	B	0/100

As shown in Table 1, coating films having low refractive indices, low reflectance and good abrasion resistance, were obtained from the coating fluids of the present invention ( $L_1$  to  $L_5$ ). Whereas, with the coatings  
5 obtained from the coating fluids of Comparative Examples ( $L_6$  to  $L_8$ ), the abrasion resistance was not sufficient, although they had low refractive indices and low reflectance.

Further, as shown in Table 2, each of the coatings  
10 obtained from the coating fluids ( $L_1$  to  $L_5$ ) had excellent antifouling properties and was excellent in adhesion to the substrate. Whereas, with coating fluid  $L_7$  of Comparative Example, the oil-based ink antifouling property was inadequate, and with coating fluid  $L_8$  of  
15 Comparative Example, both the antifouling properties and adhesion were inadequate.

#### INDUSTRIAL APPLICABILITY

The coating film of the present invention may be  
20 applied to the surface of various products for which antireflection of light is desired, including cathode ray tubes made of glass, displays for computers, mirrors having glass surface and showcases made of glass. Further, the coating film of the present invention is  
25 highly hard and excellent in abrasion resistance and has a practically sufficient antifouling property, and it is possible to form such a coating film by baking at a low

temperature at a level of about 100°C. Thus, it is useful particularly for an antireflection film for liquid crystal TV or display monitors.